

IN THE SPECIFICATION:

Please insert the following new paragraph [0032.1]:

[0032.1] FIG. 12A schematically depicts contacts that have been coated with multiple regions or layers of conductive material;

Please amend paragraph [0077] as follows:

[0077] Each core 18 may then be plated or otherwise coated with conductive material to form a conductive coating 20 thereon, as shown in FIG. 12. Conductive coating 20 may be formed by way of known electrolytic, electroless, or immersion plating techniques. If core 18 is formed from a nonmetallic material, such as a dielectric photopolymer, it may be necessary to prepare or treat the surface of core 18, as known in the art, prior to forming conductive coating 20 thereon. Conductive coating 20 may include one or more sublayers or subregions 20a, 20b, etc., as shown in FIG. 12A. For example, if core 18 is formed from a dielectric material, conductive coating 20 may include a conductive sublayer 20a (e.g., a sublayer of copper, aluminum, etc.), as well as a barrier sublayer 20b (e.g., a sublayer of nickel) and a noble sublayer 20c (e.g., a sublayer of gold). As another example, if core 18 comprises a conductive material, conductive coating 20 may include a barrier sublayer and a noble sublayer. Plating mask 120 prevents other features on substrate 100 from being plated.